

PACK4EU Final event- June 18th
World Trade Center – Grenoble, France
& EPoSS Annual Forum- Cork, Ireland- Online event



Funded by
the European Union

The project is supported by the CHIPS-JU and its members

14h00- 14h05 PACK4EU Final workshop - Opening by Jean-Marc YANNOU (ASE)- Auditorium

14h05- 14h30 “Semiconductor and packaging landscape in EU amidst a global geopolitical context”, Emilie Jolivet (Yole) and Stefan Chitoraga (Yole).

14h30-14h40: “European Chips Act – First of a kind fabs, IPCEI and Chips4 EU initiative – but what about packaging?”, Elisabeth Steimetz (EPoSS, VDI-VDE).

14h40- 14h45: “The European INFRACHIP program”, Tony Maindron, (Minalogic).

14h45-14h50: “The PEPR Électronique Packaging Concerted Action”, Hugues Granier (LAAS-CNRS, University of Toulouse), David Henry (Univ. Grenoble Alpes, CEA).

14h50 – 15h20: “Pack4EU project final recommendations”, Regis Hamelin, Pack4EU coordinator (Blumorpho)

15h20- 15h40: “Lab to Fab Accelerators Proposal: a Chiplet Integration Platform”, Renaud de LANGLADE (EPoSS and Chips JU, Board member).

15h40 – 16h00 Coffee break (Exhibition Hall) sponsored by PACK4EU

16h00 – 17h00 Pannel session- “Reactions to the PACK4EU Final recommendations”

Chairman, Renaud de LANGLADE (EPoSS and Chips JU, Board member) and Sanae BOULAY (IMAPS FR, NXP)

- Laurent Herard- ST
- Jean-René Lèquepeys- CEA
- Didier Floriot- Thales
- Mario Ibrahim- AT&S
- Fabien Corsat- ITEN
- Eric Fribourg-Blanc, Chips Joint Undertaking
- French PA, DGE tbc
- Regional PA: Rhones Alpes tbc.

17h00 – 17h50 Open discussion with the audience

17h50 – 18h00 Closing remarks by Jean-Marc YANNOU (ASE)

18h00 -19h15 PACK4EU Cocktail with Minapad exhibitors

REGISTRATION MANDATORY & Free of Charge via IMAPS website: [imaps \(imapsfrance.org\)](http://imaps.fr)

Or via email : imaps.france@orange.fr

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EPoSS.

European Association on
Smart Systems Integration